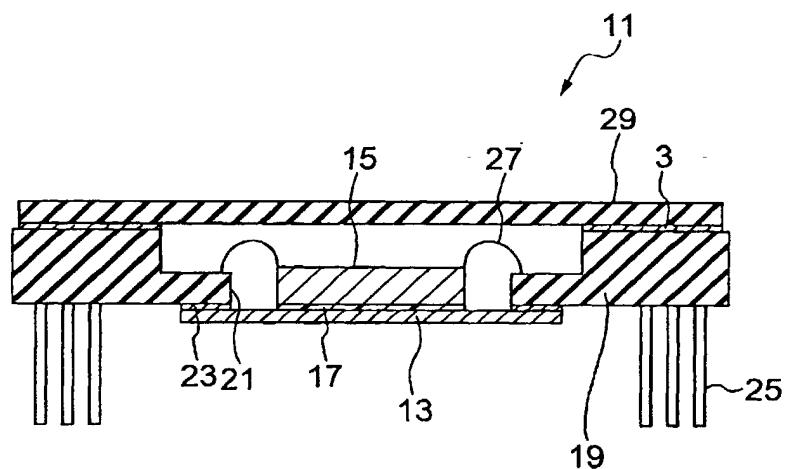


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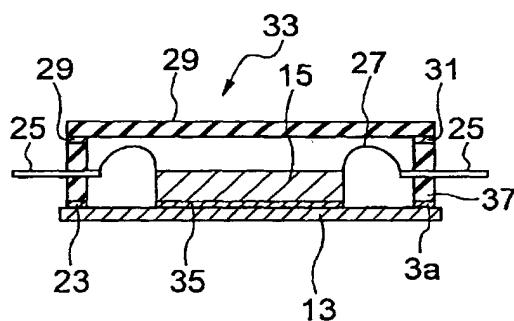
OSADA et al Q67726
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SUBSTRATE FOR MOUNTING A
SEMICONDUCTOR, METHOD OF PRODUCING ..
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FIG. 1



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FIG. 2



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FIG. 3

<BEFORE ROLLING>

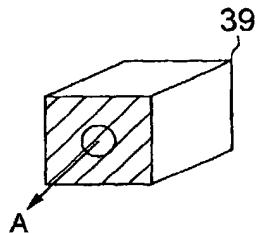


FIG. 4

ENLARGED VIEW
OF PART A

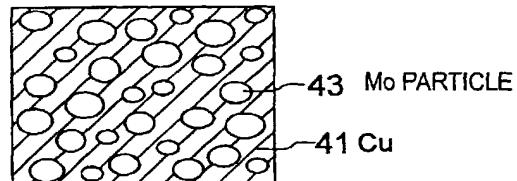


FIG. 5

<AFTER ROLLING>

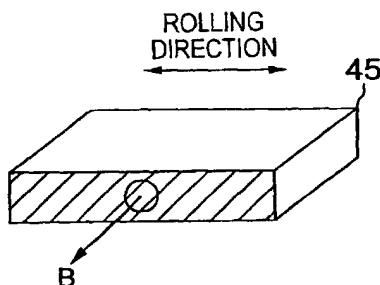
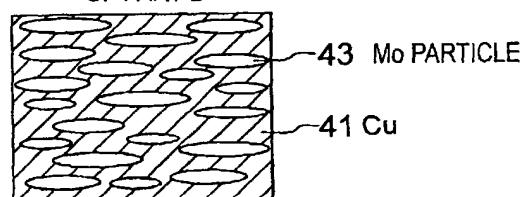


FIG. 6

ENLARGED VIEW
OF PART B



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FIG. 7

FIGURE 7 2000 T

